## Wide Bandwidth <br> Low Voltage LanSwitch Quad 2:1 MUX/DEMUX

## Product Features:

- Replaces mechanical relays
- High-performance, low-cost solution for switching between different LAN signals
- Ultra-low quiescent power (0.1 $\mu \mathrm{A}$ typical)
- Low crosstalk: -40 dB @ 30 Mbps
- Low insertion loss or on-resistance: $3 \Omega$ typical
- Single extended supply operation up to $6.2 \mathrm{~V} \pm 5 \%$
- Off isolation: - $30 \mathrm{~dB} @ 30 \mathrm{Mbps}$
- Wide bandwidth data rates > 200 Mbps
- Packages available:
- 16-pin 150 mil wide plastic SOIC (W)
- 16-pin 150 mil wide plastic QSOP (Q)
- 20-pin 173 mil wide plastic TSSOP (L)


## Product Description:

Pericom Semiconductor's PI5L series of logic circuits are produced in the Company's advanced submicron CMOS technology.
The PI5L100 is a Quad 2:1 multiplexer/demultiplexer LanSwitch with three-state outputs. This device can be used for switching between various standards, such as 10 Base-T, 100 Base-T, 100VG-AnyLAN or Token Ring. Generally, this part can be used to replace mechanical relays in low voltage LAN applications that have phsical layer, unshielded twisted pair media (UTP) with either CAT 3 or CAT 5 grade cable.
The PI5L100 is powered from a 6.2 V Zener voltage to reduce the insertion loss.

## Logic Block Diagram



## Truth Table ${ }^{(1)}$

| $\overline{\mathbf{E}}$ | S | YA | YB | YC | YD | Function |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| H | X | Hi-Z | Hi-Z | Hi-Z | Hi-Z | Disable |
| L | L | IA0 | IB0 | IC0 | ID0 | S = 0 |
| L | H | IA1 | IB1 | IC1 | ID1 | S $=1$ |

## Note:

1. $\mathrm{H}=$ High Voltage Level

L = Low Voltage Level

16-Pin Product Configuration

| $\begin{aligned} \text { S } & - \\ \text { IAO } & - \\ \text { IA1 } & - \\ \text { YA } & - \\ \text { IBO } & - \\ \text { IB1 } & - \\ \text { YB } & - \\ \text { GND } & - \end{aligned}$ |  |
| :---: | :---: |

20-Pin Product Configuration


## Product Pin Description

| Pin Name | Description |
| :--- | :--- |
| IAn-IDn | Data Inputs |
| S | Select Inputs |
| $\overline{\mathrm{E}}$ | Enable |
| YA-YD | Data Outputs |
| GND | Ground |
| Vcc | Power |

## Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

| Storage Temperature ....................................................... $-65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$Ambient Temperature with Power Applied ............................. $0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}$Supply Voltage to Ground Potential (Inputs \& Vcc Only) ........ -0.5 V to +7.0 VSupply Voltage to Ground Potential (Outputs \& D/O Only) ...... -0.5 V to +7.0 VDC Input Voltage ............................................................. -0.5 V to +7.0 VDC Output Current ............................................................................. 120 mAPower Dissipation .............................................................................. 0.5 W |  |
| :---: | :---: |
|  |  |
|  |  |
|  |  |
|  |  |
|  |  |
|  |  |

## Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC Electrical Characteristics (Over the Operating Range, $\mathrm{TA}=0^{\circ} \mathrm{C}$ to $+70^{\circ} \mathrm{C}, \mathrm{VCC}=6.2 \mathrm{~V},+5 \%,-2 \%$ )

| Parameters | Description | Test Conditions ${ }^{(1)}$ | Min. | Typ ${ }^{(2)}$ | Max. | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Vif | Input HIGH Voltage | Guaranteed Logic HIGH Level | 2.0 | - | - | V |
| VIL | Input LOW Voltage | Guaranteed Logic LOW Level | -0.5 | - | 0.8 | V |
| IIH | Input HIGH Current | $\mathrm{VCC}_{\text {c }}=$ Max., $\mathrm{V}_{\text {IN }}=\mathrm{VCC}^{\text {c }}$ | - | - | $\pm 1$ | $\mu \mathrm{A}$ |
| IIL | Input LOW Current | $\mathrm{VCC}^{\text {}}=$ Max., $\mathrm{V}_{\text {IN }}=\mathrm{GND}$ | - | - | $\pm 1$ | $\mu \mathrm{A}$ |
| IozH | High Impedance Output Current | $0 \leq \mathrm{A}, \mathrm{B} \leq \mathrm{VCC}$ | - | - | $\pm 1$ | $\mu \mathrm{A}$ |
| VIK <br> V | Clamp Diode Voltage | VCC $=$ Min., $\operatorname{IIN}=-18 \mathrm{~mA}$ |  | - | -0.7 | -1.2 |
| Ios | Short Circuit Current ${ }^{(3)}$ | $\mathrm{A}(\mathrm{B})=0 \mathrm{~V}, \mathrm{~B}(\mathrm{~A})=\mathrm{VCC}$ | 100 | - | - | mA |
| VH | Input Hysteresis at Control Pins | - | - | 150 | - | mV |
| Von | Switch On Voltage | $\begin{aligned} & \text { VIN }=4.5 \mathrm{~V}, \mathrm{E}=\mathrm{LOW} \\ & \text { See Figure } 10, \mathrm{R}_{\mathrm{L}}=100 \Omega \end{aligned}$ | $3.7{ }^{(4)}$ | $4.06{ }^{(5)}$ | - | V |
| Ron ${ }^{(6)}$ | M1 Switch On Resistance | Calculated from Von | 19 | 11.2 | - | $\Omega$ |
| Ros ${ }^{(7)}$ | M2 Switch On Resistance | $\begin{aligned} & \text { VIN }=4.5 \mathrm{~V}, \mathrm{E}=\mathrm{LOW} \\ & \text { See Figure } 10, \mathrm{RL}=100 \Omega \end{aligned}$ | 2.0 | 3.0 | - | $\Omega$ |
| $\Delta$ RON | On Resistance Match | VIN $=4.5 \mathrm{~V}, \mathrm{E}=\mathrm{LOW}$ | - | 1.0 | - | $\Omega$ |

## Notes:

1. For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at $\mathrm{Vcc}=6.2 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ ambient temperature.
3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
4. Von $(\mathrm{min})$ value is at $\mathrm{Vcc}=6.1 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=70^{\circ} \mathrm{C}$.
5. The expected AC Von value is about 125 mV higher than the DC Von value using the similar test circuit in Figure 10 with Vin swing from 0.0V to 4.5 V at 10 MHz sine wave.
6. The value of Ron of M1 is calculated with the equvalent mathematical formula of the test circuit in Figure 10.
```
\(\operatorname{RoN}(\mathrm{M} 1)=\frac{\mathrm{VIN}-\mathrm{VON}}{\mathrm{ION}}\)
where
\[
\begin{aligned}
& \text { ION }=\frac{\text { VoN }}{\text { RL }+ \text { RON (M2) }} \\
& \text { with RON }(\mathrm{M} 2)=3 \mathrm{Ohm}
\end{aligned}
\]
```

7. This parameter is determined by device characterization but is not production tested.

Capacitance ( $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{f}=1 \mathrm{MHz}$ )

| Parameters $^{(1)}$ | Description | Test Conditions | Typ | Max. | Units |
| :--- | :--- | :--- | :---: | :---: | :---: |
| Cin | Input Capacitance | Vin $=0 \mathrm{~V}$ |  | 6 | pF |
| CoFF | Capacitance, Switch Off | VIN $=0 \mathrm{~V}$ |  | 6 | pF |
| Con | Capacitance, Switch On | Vin $=0 \mathrm{~V}$ |  | 8 | pF |

## Note:

1. This parameter is determined by device characterization but is not production tested.

## Power Supply Characteristics

| Parameters | Description | Test Conditions ${ }^{(1)}$ |  | Min. | Typ ${ }^{(2)}$ | Max. | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Icc | Quiescent Power Supply Current | $V_{C C}=$ Max . | VIN $=$ GND or $\mathrm{VCC}^{\text {c }}$ | - | 0.1 | 3.0 | $\mu \mathrm{A}$ |
| $\Delta \mathrm{Icc}$ | Supply Current per Input @ TTL HIGH | $\mathrm{VCC}=\mathrm{Max}$. | $\mathrm{V}_{\text {IN }}=3.4 \mathrm{~V}^{(3)}$ | - | - | 2.5 | mA |
| ICCD | Supply Current per Input per $\mathrm{MHz}^{(4)}$ | VCC = Max., <br> Input Pins Open $\overline{\mathrm{E}}=\mathrm{GND}$ <br> Control Input Toggling 50\% Duty Cycle |  | - | - | 0.25 | $\begin{aligned} & \mathrm{mA} / \\ & \mathrm{MHz} \end{aligned}$ |

## Notes:

1. For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device.
2. Typical values are at $\mathrm{Vcc}=6.2 \mathrm{~V},+25^{\circ} \mathrm{C}$ ambient.
3. Per TTL driven input ( $\mathrm{V}_{\mathrm{IN}}=3.4 \mathrm{~V}$, control inputs only); A and B pins do not contribute to Icc.
4. This current applies to the control inputs only and represent the current required to switch internal capacitance at the specified frequency. The A and B inputs generate no significant AC or DC currents as they transition. This parameter is not tested, but is guaranteed by design.

## Switching Characteristics over Operating Range

| Parameters | Description | Conditions ${ }^{(1)}$ | PI5L100 |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | Com. |  |  |  |
|  |  |  | Min | Typ | Max |  |
| tIY | Propagation Delay ${ }^{(2,3)}$ <br> In to Y | $\begin{aligned} & \mathrm{CL}=50 \mathrm{pF} \\ & \mathrm{RL}_{\mathrm{L}}=500 \Omega \end{aligned}$ | - | - | 0.25 | ns |
| tSY | Bus Enable Time S to Y |  | 0.5 | - | 5.2 | ns |
| $\begin{aligned} & \text { tPHZ } \\ & \text { tPLZ } \\ & \hline \end{aligned}$ | Bus Disable Time $\overline{\mathrm{E}}$ to Y |  | 0.5 | - | 5.0 | ns |
| tey | Bus Disable Time $\overline{\mathrm{E}}$ to Y |  | 0.5 | - | 4.8 | ns |
| Xtalk (Dif) | Differential Crosstalk ${ }^{(2)}$ | $\begin{aligned} & \mathrm{R}_{\mathrm{L}}=100 \Omega \\ & \mathrm{f}=10 \mathrm{MHz} \end{aligned}$ <br> See Figure 11 | -40 | -60 | - | dB |
| XtaLK | Crosstalk | $\begin{aligned} & \mathrm{R}_{\mathrm{L}}=100 \Omega \\ & \mathrm{f}=30 \mathrm{MHz} \\ & \text { See Figure } 9 \end{aligned}$ | - | -40 | - | dB |
| OIRR | Off Isolation | $\begin{aligned} & \mathrm{RL}=100 \Omega \\ & \mathrm{f}=30 \mathrm{MHz} \\ & \text { See Figure } 6 \end{aligned}$ | - | -30 | - | dB |
| Bw | -3 dB Bandwidth | $\mathrm{R}_{\mathrm{L}}=100 \Omega$ <br> See Figure 9 | - | 216 | - | MHz |
| ton | Turn On Time | $\begin{aligned} & \mathrm{R}_{\mathrm{L}}=100 \Omega \\ & \mathrm{CL}=35 \mathrm{pF} \end{aligned}$ <br> See Figure 8 | - | 11 | - | ns |
| toff | Turn Off Time |  | - | 11 | - | ns |

## Notes:

1. See test circuit and wave forms.
2. This parameter is guaranteed but not tested.
3. The bus switch contributes no propagational delay other than the RC delay of the ON resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25 ns for 50 pF load. Since this time constant is much smaller than the rise/fall times of typical driving signals, it adds very little propagational delay to the system. Propagational delay of the bus switch when used in a system is determined by the driving circuit on the driving side of the switch and its interaction with the load on the driven side.


Figure 3. Ron vs Input Voltage over Temperature $\left(\right.$ Ron at Vcc $\left.=6.1 \mathrm{~V} @ 75^{\circ} \mathrm{C}\right)$


Figure 4. Ron vs Input Voltage $\left(\right.$ Ron at $\left.\mathrm{Vcc}=6.2 \mathrm{~V} @ 25^{\circ} \mathrm{C}\right)$


Figure 5. Gain/Phase vs Frequency


Figure 6. Off Isolation vs Frequency


Figure 7. Crosstalk vs Frequency

## APPLICATIONS SECTION

## LAN Switch Applications

The PI5L100 was designed to switch between various standards such as 10Base-T, 100Base-T, 100VGAnyLAN, and Token Ring. Also general purpose applications such as loopback, line termination, and line clamps that might normally use mechanical relays are also ideal uses for this LAN Switch (see Figure 11 applications). Generally speaking, this LAN Switch can be used for data rates to 200 Mbps and data signal levels from 0 V to 4.5 V .

| LAN Standards | Data Rate per twisted pair (UTP) |
| :--- | :--- |
| 10Base-T | 10 Mbps |
| 100Base-T | 100 Mbps |
| 100VG-AnyLAN | 25 Mbps |

## Differential Crosstalk ...Xtalk (dif)

Adjacent pins cause the most crosstalk because of the interlead package capacitance which is generally in the order of 0.5 pF (pin-to-pin). It can be seen in Figure 11 that this Evaluation (EV) Board schematic uses four pairs of switches. The pair 1B/2B are RX1 that connect to YA and YB . The second pair 3B/4B are TX1 and connect to YC and YB. Pairs 3 and 4 are grounded for this differential crosstalk test. The purpose of this EV board is to determine the amont of crosstalk between the transmit and receive pairs in a full duplex application. Figure 15 shows the scope waveforms. Traces 1 and 2 are single ended inputs to the differential inputs of the DUT. Trace 3 is the differential Xtalk output which equates to 20LOG Vout/Vin $=20 \mathrm{LOG} 30 \mathrm{mV} / 5 \mathrm{~V}=-$ 44 dB . Since the edge rate is 2 ns , the effective input frequency is equal to $0.3 / \mathrm{tr}$ which is $\sim 150 \mathrm{MHz}$. So the
approximate Differential Crosstalk at 150 MHz is -44 dB .
Because pins measured are not adjacent, the differential crosstalk is typically > 60 dB at 10 MHz . The load resistor (RL) used was 100 ( to match the UTP impedance). Increasing the data rate or RL will also increase differential crosstalk.

## Vcc Bias Voltage vs Ron

To keep Ron to a minimum, it is recommended that the Vcc voltage be increased to a voltage between +6.0 V and +6.5 V (see Figure 13). The Ron vs Vin curve shows the effect of on-resistance and input voltage which is exponential. Ideally an input voltage between 0.2 V and 3.6 V will keep RON in the flat part of the curve ( $\Delta$ Ron or flatness is $\sim 2 \Omega$ ).

## Signal Distortion

Distortion of the input signal is equated to 20LOG $\Delta$ RON/ RL. So keeping RON flat as the data signal level varies is critical to low distortion. It should also be noted that increasing the data rate increases harmonic distortion which also effects the signal amplitude.

## Evaluation Board

Figure 14 shows the layout for an EV board that can be used for evaluation. This is a 2-layer board and is oneinch square.

## Test Circuits



Figure 8. Switching Time


Figure 9. Gain/Phase Crosstalk, Off Isolation


Figure 10. Switch ON Voltage Test Circuit


Figure 11. Differential Crosstalk Measurement


Figure 12a. Full Duplex Transceiver


Figure 12d. Line Clamp


Figure 13. Vec Bias Current


Figure 14a. Crosstalk EV Board

Figure 14b. Component Side



Figure 14c. Solder Side


## Figure 15. Crosstalk Waveform

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